

OK TO ENTER
MDF 11/10/2006

Docket No.: X2007.0158
(PATENT)

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of:
Kenichi Shirasaka

Application No.: 10/811,999

Confirmation No.: 2679

Filed: March 30, 2004

Art Unit: 2814

For: METHOD OF MANUFACTURING A
SEMICONDUCTOR PACKAGE USING
LEAD FRAME HAVING THROUGH
HOLES OR HOLLOWES THEREIN

Examiner: C. M. D. Pizarro

AMENDMENT AFTER FINAL ACTION UNDER 37 C.F.R. 1.116

MS AF
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Dear Sir:

INTRODUCTORY COMMENTS

In response to the Final Office Action dated June 29, 2006, finally rejecting claims 3, 10 and 12, reconsideration of the above-identified U.S. patent application is respectfully requested:

Listing of the Claims is included beginning on page 3 of this paper. No claims have been amended hereby. The listing of the claims has been included solely for the convenience of the Examiner.

Remarks/Arguments begin on page 8 of this paper.